

Lead Free Core Wire Product Data Sheet

Rev:2007/8/1 Ver. 5

NO	Item	Specification	Standard
1	Appearance	Bright and shiny surface finishes	
2	Alloy	Sn/Cu0.7	JIS-Z-3282
3	Melting Point	227~228°C	DSC
4	Flux Content	3.0 ±1.0%	JIS-Z-3283
5	Halide Content	Under 0.5%	J-STD-004
6	Gravity	7.3	
7	Spread ability	> 80%	JIS-Z-3197
8	Packaging	200g, 250g, 500g, 1kg , 5kg , 10kg/Rool	JIS-Z-3283
9	Diameters Tolerances	0.3~0.6± 0.05 mm , 0.8~3.0 ± 0.1 mm	JIS-Z-3283
10	Flux Type	ROL1	J-STD-004
11	Features	Excellent solder joint reliability. Superior joint strength. Excellent thermal & Mechanical fatigue resistance. Low cleaning required after solder joint	
12	Purpose	For use in applications requiring good activation.	
13	Storage, Handling, and Shelf Life:	Storage must be in a dry, non-corrosive and shine environment. Avoids the oxidant, the acid and the hydrogen peroxide. Shelf life is 2 years from date of manufacture.	

Physical Properties & Reliability Data

No	Test Item	Test Result	Test Method
1	Copper Mirror Test	PASS	IPC-TM-650, 2.3.32
2	Copper plate Corrosion	PASS	JIS-Z-3197, 6.6.1
3	S.I.R Test	1×10 ⁹ up	IPC-TM-650, 2.6.3.3
4	Electro migration Test	1×10 ⁹ ¹² up	IPC-TM-650, 2.6.14.1

ALLOY COMPOSITION

(Sn)	(Ag)	(Cu)	(Ni)	(Zn)	(Al)	(Sb)	(Fe)	(As)	(Bi)	(Cd)	(Pb)
REM.	0.10 MAX	0.5~ 0.9	0.002 MAX	0.001 MAX	0.001 MAX	0.05 MAX	0.02 MAX	0.03 MAX	0.10 MAX	0.002 MAX	0.05 MAX